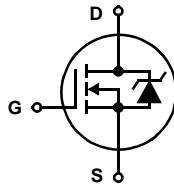


**20A, 20V, 0.027 Ohm, N-Channel, Logic Level Power MOSFETs**

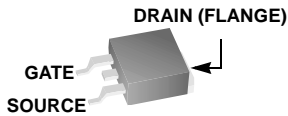
THE HUF76009 is an application-specific MOSFET optimized for switching when used as the upper switch in synchronous buck applications. The low gate charge and low input capacitance results in lower driver and lower switching losses thereby increasing the overall system efficiency.

**Symbol**

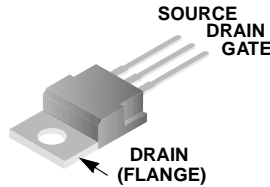


**Packaging**

HUF76009D3S  
JEDEC TO-252AA



HUF76009P3  
JEDEC TO-220AB



**Features**

- 20A, 20V
  - $r_{DS(ON)} = 0.027\Omega$ ,  $V_{GS} = 10V$
  - $r_{DS(ON)} = 0.039\Omega$ ,  $V_{GS} = 5V$
- PWM optimized for synchronous buck applications
- Fast Switching
- Low Gate Charge
  - $Q_g$  Total 11nC (Typ)
- Low Capacitance
  - $C_{ISS}$  470pF (Typ)
  - $C_{RSS}$  50pF (Typ)

**Ordering Information**

PART NUMBER	PACKAGE	BRAND
HUF76009P3	TO-220AB	76009P
HUF76009D3S	TO-252AA	76009D

NOTE: When ordering, use the entire part number. Add the suffix T to obtain the HUF76009D3S in tape and reel, e.g., HUF76009D3ST.

**Absolute Maximum Ratings**  $T_C = 25^\circ C$ , Unless Otherwise Specified

SYMBOL	PARAMETER	HUF76009P3, HUF76009D3S	UNITS
$V_{DSS}$	Drain to Source Voltage (Note 1)	20	V
$V_{DGR}$	Drain to Gate Voltage ( $R_{GS} = 20k\Omega$ ) (Note 1)	20	V
$V_{GS}$	Gate to Source Voltage	$\pm 20$	V
$I_D$	Drain Current		
$I_D$	Continuous ( $T_C = 25^\circ C$ , $V_{GS} = 10V$ ) (Figure 2)	20	A
$I_D$	Continuous ( $T_C = 100^\circ C$ , $V_{GS} = 5V$ )	16	A
$I_{DM}$	Pulsed Drain Current	Figure 4	A
$P_D$	Power Dissipation	41	W
	Derate Above $25^\circ C$	0.33	W/ $^\circ C$
$T_J, T_{STG}$	Operating and Storage Temperature	-55 to 150	$^\circ C$
$T_L$	Maximum Temperature for Soldering		
$T_{pkg}$	Leads at 0.063in (1.6mm) from Case for 10s	300	$^\circ C$
	Package Body for 10s, See Techbrief TB334	260	$^\circ C$

**THERMAL SPECIFICATIONS**

$R_{\theta JC}$	Thermal Resistance Junction to Case, TO-220, TO-252	3.04	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-220	62	$^\circ C/W$
	Thermal Resistance Junction to Ambient TO-252	100	$^\circ C/W$

NOTE:

1.  $T_J = 25^\circ C$  to  $125^\circ C$ .

**CAUTION:** Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

## HUF76009P3, HUF76009D3S

### Electrical Specifications $T_C = 25^\circ\text{C}$ , Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS	
<b>OFF STATE SPECIFICATIONS</b>							
Drain to Source Breakdown Voltage	$BV_{DSS}$	$I_D = 250\mu\text{A}$ , $V_{GS} = 0\text{V}$ (Figure 11)	20	-	-	V	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 20\text{V}$ , $V_{GS} = 0\text{V}$	-	-	1	$\mu\text{A}$	
		$V_{DS} = 20\text{V}$ , $V_{GS} = 0\text{V}$ , $T_C = 150^\circ\text{C}$	-	-	250	$\mu\text{A}$	
Gate to Source Leakage Current	$I_{GSS}$	$V_{GS} = \pm 20\text{V}$	-	-	$\pm 100$	nA	
<b>ON STATE SPECIFICATIONS</b>							
Gate to Source Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$ , $I_D = 250\mu\text{A}$ (Figure 10)	1	-	3	V	
Drain to Source On Resistance	$r_{DS(ON)}$	$I_D = 20\text{A}$ , $V_{GS} = 10\text{V}$ (Figures 8, 9)	-	0.022	0.027	$\Omega$	
		$I_D = 16\text{A}$ , $V_{GS} = 5\text{V}$ (Figure 8)	-	0.032	0.039	$\Omega$	
<b>SWITCHING SPECIFICATIONS (<math>V_{GS} = 5\text{V}</math>)</b>							
Turn-On Time	$t_{ON}$	$V_{DD} = 10\text{V}$ , $I_D = 16\text{A}$ $V_{GS} = 5\text{V}$ , $R_{GS} = 27\Omega$ (Figures 14, 18, 19)	-	-	186	ns	
Turn-On Delay Time	$t_{d(ON)}$		-	9	-	ns	
Rise Time	$t_r$		-	115	-	ns	
Turn-Off Delay Time	$t_{d(OFF)}$		-	19	-	ns	
Fall Time	$t_f$		-	34	-	ns	
Turn-Off Time	$t_{OFF}$		-	-	80	ns	
<b>SWITCHING SPECIFICATIONS (<math>V_{GS} = 10\text{V}</math>)</b>							
Turn-On Time	$t_{ON}$	$V_{DD} = 10\text{V}$ , $I_D = 20\text{A}$ $V_{GS} = 10\text{V}$ , $R_{GS} = 27\Omega$ (Figures 15, 18, 19)	-	-	150	ns	
Turn-On Delay Time	$t_{d(ON)}$		-	5.3	-	ns	
Rise Time	$t_r$		-	95	-	ns	
Turn-Off Delay Time	$t_{d(OFF)}$		-	37	-	ns	
Fall Time	$t_f$		-	33	-	ns	
Turn-Off Time	$t_{OFF}$		-	-	105	ns	
<b>GATE CHARGE SPECIFICATIONS</b>							
Total Gate Charge at 10V	$Q_{g(TOT)}$	$V_{GS} = 0\text{V}$ to 10V	$V_{DD} = 10\text{V}$ , $I_D = 16\text{A}$ , $I_{g(REF)} = 1.0\text{mA}$ , (Figures 13, 16, 17)	-	10.7	13	nC
Total Gate Charge at 5V	$Q_{g(TOT)}$	$V_{GS} = 0\text{V}$ to 5V		-	5.7	6.9	nC
Threshold Gate Charge	$Q_{g(TH)}$	$V_{GS} = 0\text{V}$ to 1V		-	0.5	0.6	nC
Gate to Source Gate Charge	$Q_{gs}$			-	1.7	-	nC
Gate to Drain "Miller" Charge	$Q_{gd}$			-	2.2	-	nC
<b>CAPACITANCE SPECIFICATIONS</b>							
Input Capacitance	$C_{ISS}$	$V_{DS} = 20\text{V}$ , $V_{GS} = 0\text{V}$ , $f = 1\text{MHz}$ (Figure 12)	-	470	-	pF	
Output Capacitance	$C_{OSS}$		-	350	-	pF	
Reverse Transfer Capacitance	$C_{RSS}$		-	50	-	pF	

### Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	$V_{SD}$	$I_{SD} = 20\text{A}$	-	-	1.25	V
		$I_{SD} = 10\text{A}$	-	-	1.0	V
Reverse Recovery Time	$t_{rr}$	$I_{SD} = 16\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	33	ns
Reverse Recovered Charge	$Q_{RR}$	$I_{SD} = 16\text{A}$ , $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	-	30	nC

Typical Performance Curves

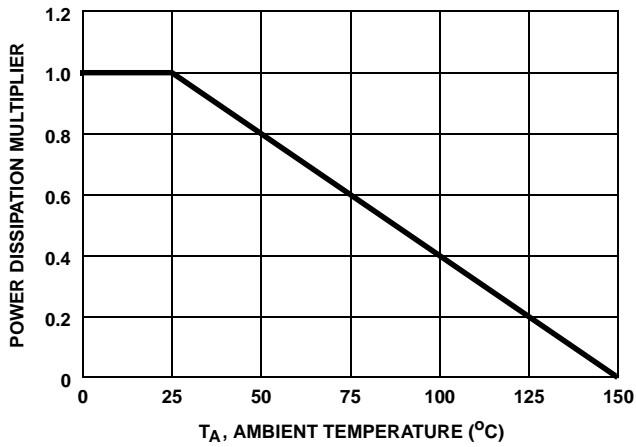


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

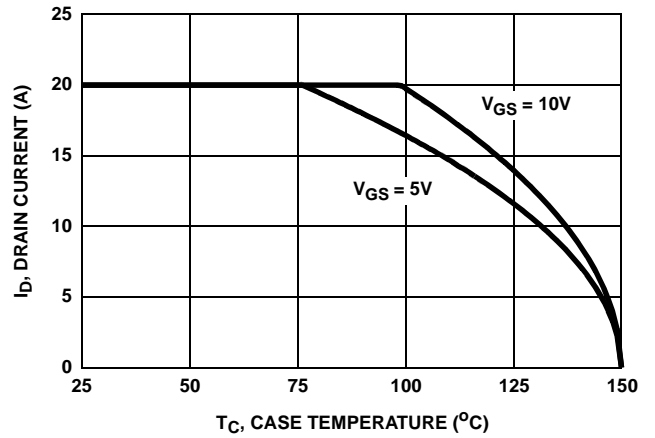


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

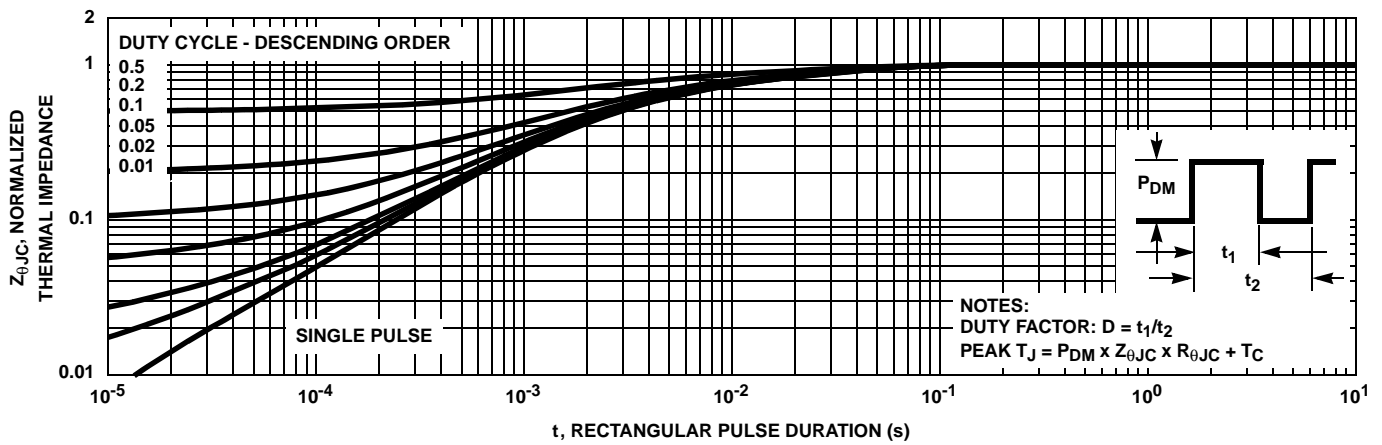


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

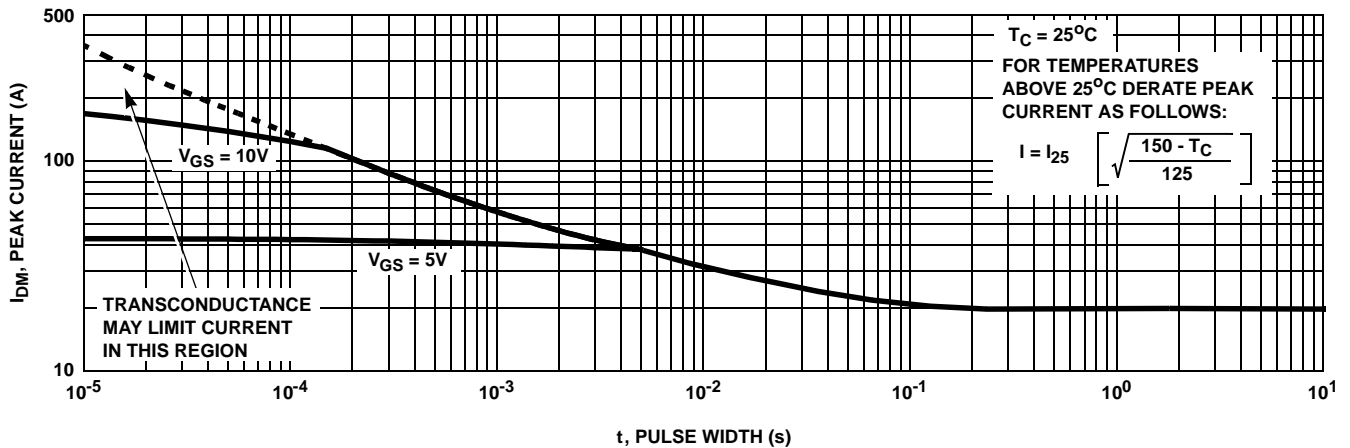


FIGURE 4. PEAK CURRENT CAPABILITY

Typical Performance Curves (Continued)

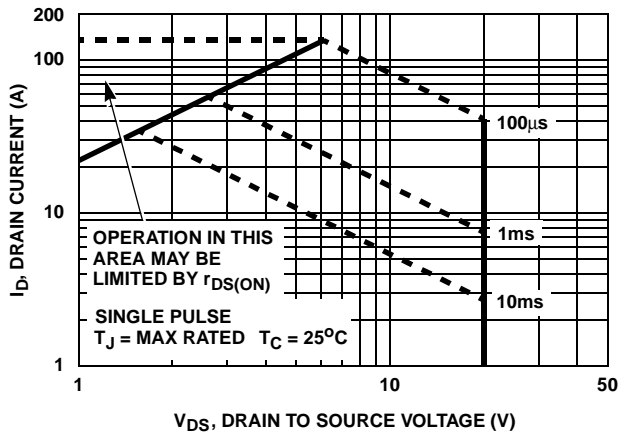


FIGURE 5. FORWARD BIAS SAFE OPERATING AREA

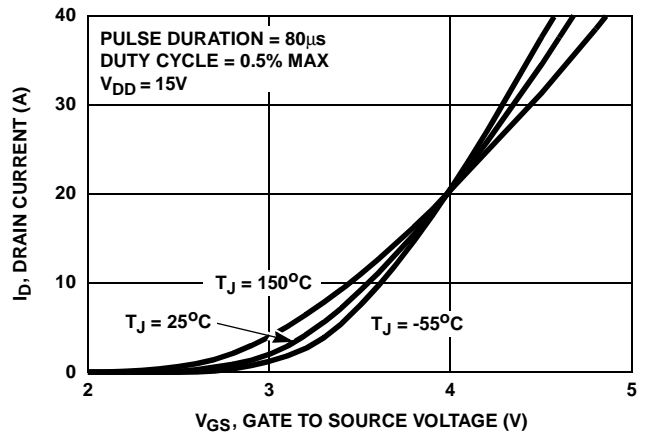


FIGURE 6. TRANSFER CHARACTERISTICS

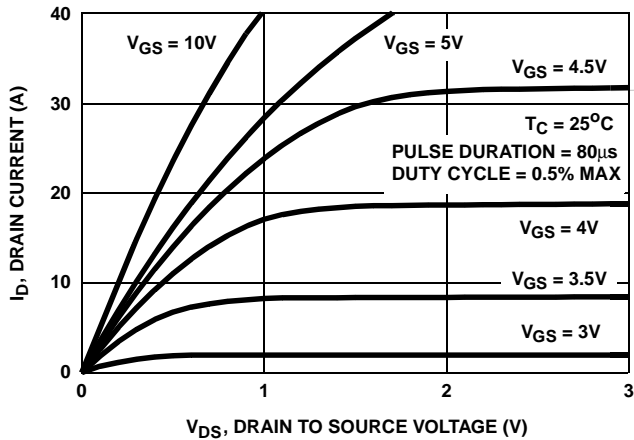


FIGURE 7. SATURATION CHARACTERISTICS

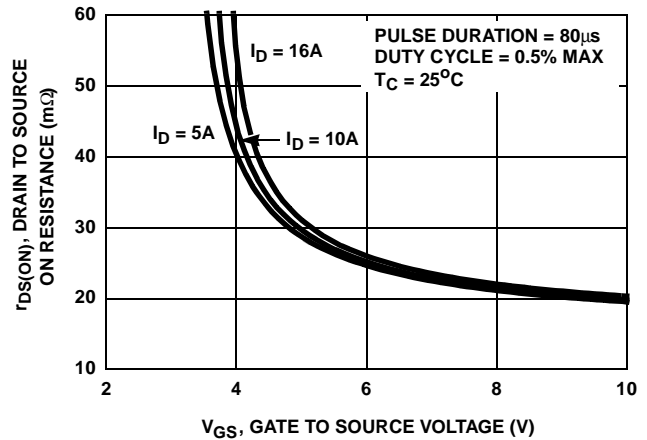


FIGURE 8. DRAIN TO SOURCE ON RESISTANCE vs. GATE VOLTAGE AND DRAIN CURRENT

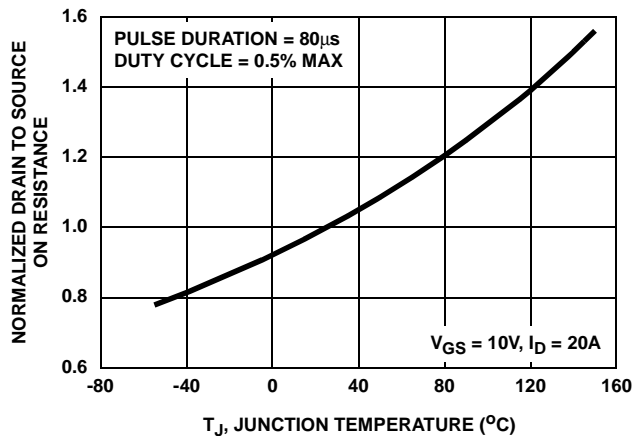


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs. JUNCTION TEMPERATURE

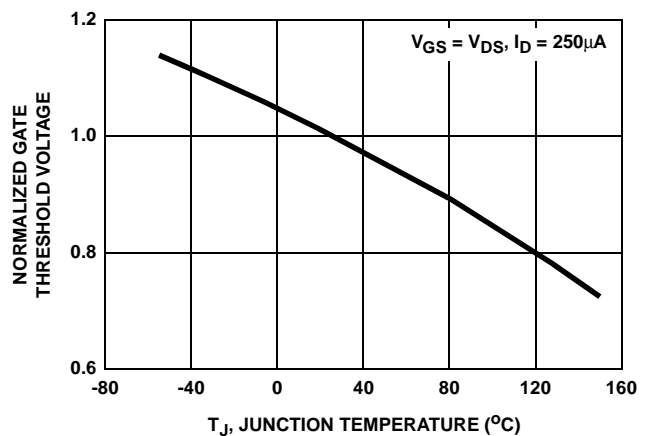


FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs. JUNCTION TEMPERATURE

Typical Performance Curves (Continued)

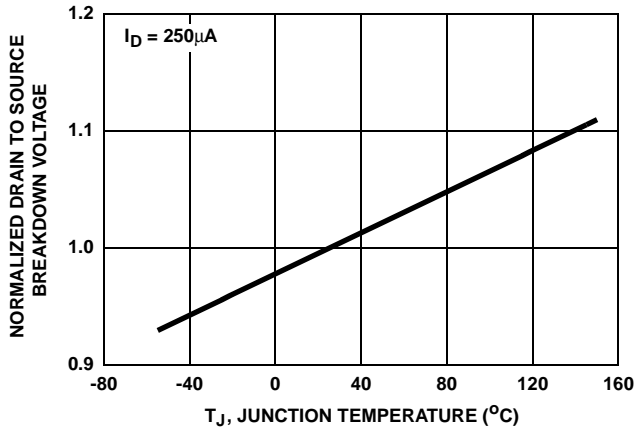


FIGURE 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

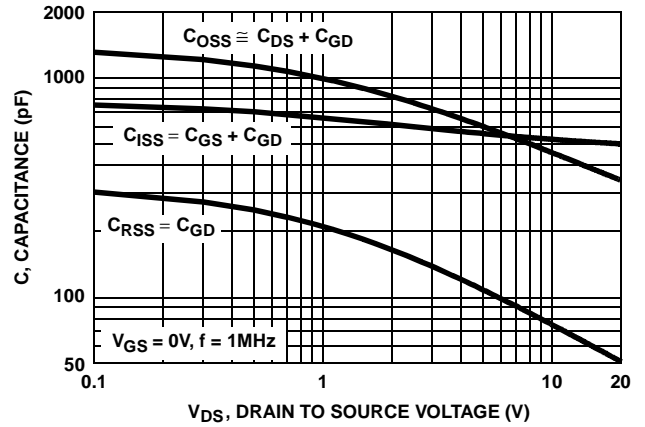
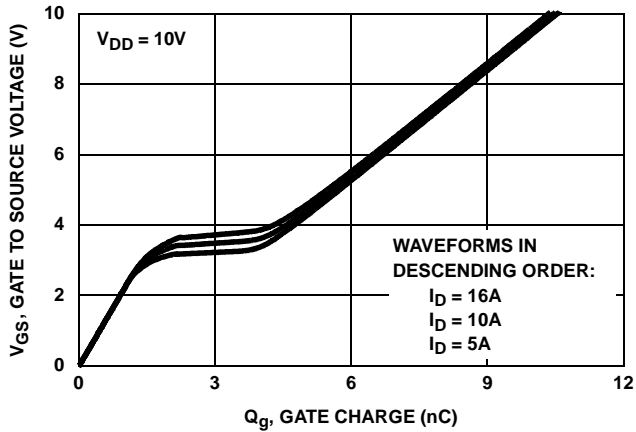


FIGURE 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260.

FIGURE 13. GATE CHARGE WAVEFORMS FOR CONSTANT GATE CURRENT

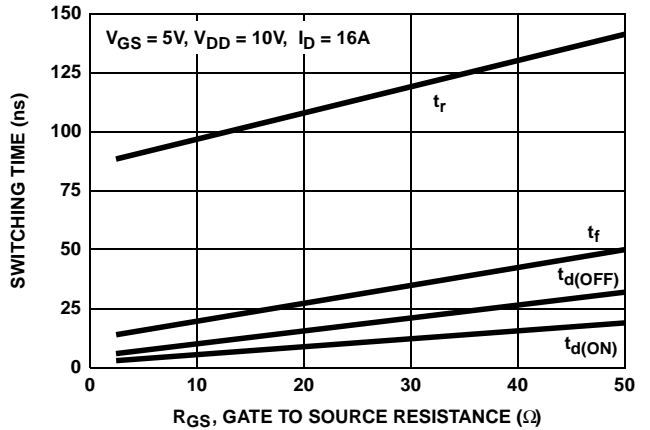


FIGURE 14. SWITCHING TIME vs GATE RESISTANCE

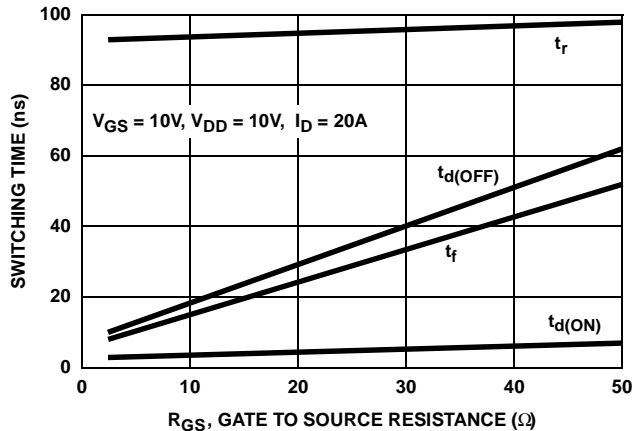


FIGURE 15. SWITCHING TIME vs GATE RESISTANCE

Test Circuits and Waveforms

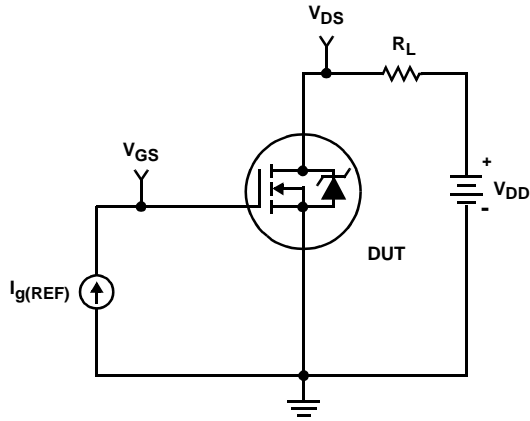


FIGURE 16. GATE CHARGE TEST CIRCUIT

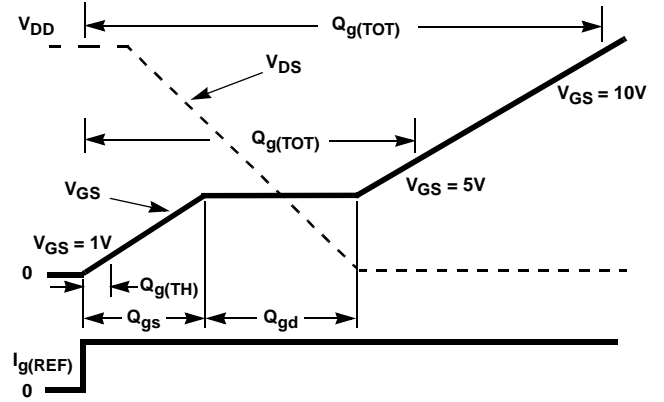


FIGURE 17. GATE CHARGE WAVEFORMS

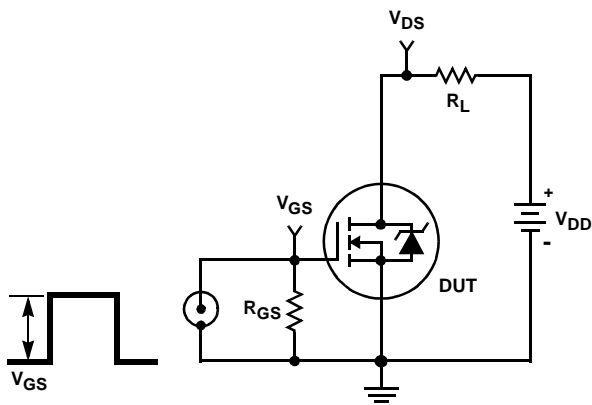


FIGURE 18. SWITCHING TIME TEST CIRCUIT

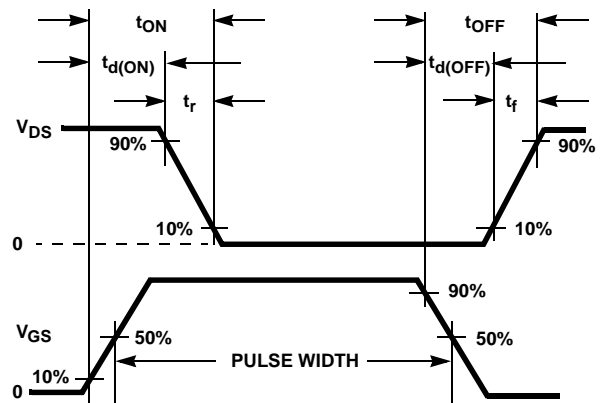


FIGURE 19. SWITCHING TIME WAVEFORM

# HUF76009P3, HUF76009D3S

## PSpICE Electrical Model

.SUBCKT HUF76009P3 2 1 3 ; rev 16 March 2000

CA 12 8 5.6e-10  
 CB 15 14 5.0e-10  
 CIN 6 8 4.5e-10

DBODY 7 5 DBODYMOD  
 DBREAK 5 11 DBREAKMOD  
 DPLCAP 10 5 DPLCAPMOD

EBREAK 11 7 17 18 25.9  
 EDS 14 8 5 8 1  
 EGS 13 8 6 8 1  
 ESG 6 10 6 8 1  
 EVTHRES 6 21 19 8 1  
 EVTEMP 20 6 18 22 1

IT 8 17 1

LDRAIN 2 5 1.0e-9  
 LGATE 1 9 4.6e-9  
 LSOURCE 3 7 4.7e-9

MMED 16 6 8 8 MMEDMOD  
 MSTRO 16 6 8 8 MSTROMOD  
 MWEAK 16 21 8 8 MWEAKMOD

RBREAK 17 18 RBREAKMOD 1  
 RDRAIN 50 16 RDRAINMOD 1.0e-3  
 RGATE 9 20 4.0  
 RLDRAIN 2 5 10  
 RLGATE 1 9 46  
 RLSOURCE 3 7 47  
 RSLC1 5 51 RSLCMOD 1e-6  
 RSLC2 5 50 1e3  
 RSOURCE 8 7 RSOURCEMOD 1.4e-2  
 RVTHRES 22 8 RVTHRESMOD 1  
 RVTEMP 18 19 RVTEMPMOD 1

S1A 6 12 13 8 S1AMOD  
 S1B 13 12 13 8 S1BMOD  
 S2A 6 15 14 13 S2AMOD  
 S2B 13 15 14 13 S2BMOD

VBAT 22 19 DC 1

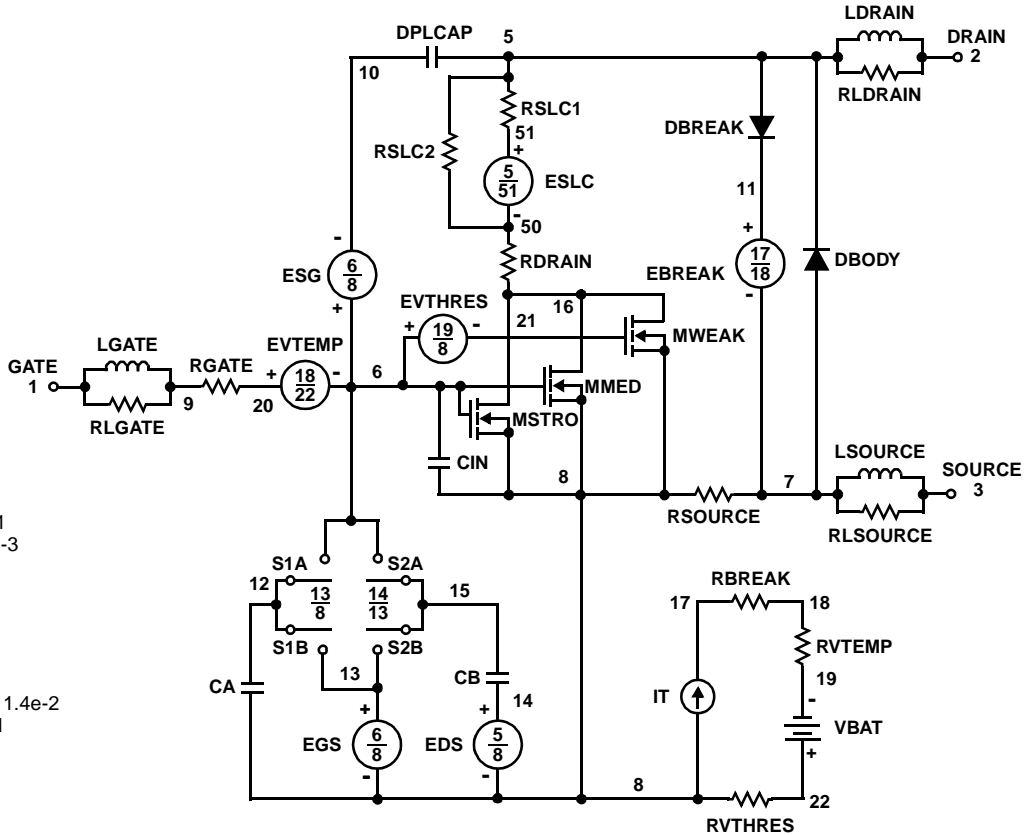
ESLC 51 50 VALUE={(V(5,51)/ABS(V(5,51)))\*(PWR(V(5,51))/(1e-6\*70),3))}

.MODEL DBODYMOD D (IS = 3.4e-13 RS = 1.0e-2 TRS1 = 2e-3 TRS2 = 8e-7 CJO = 1.05e-9 TT = 1.18e-8 XTI = 5 M = 0.42)  
 .MODEL DBREAKMOD D (RS = 1.3e-1 TRS1 = 0 TRS2 = 0)  
 .MODEL DPLCAPMOD D (CJO = 3.2e-10 IS = 1e-30 N = 10 M = 0.6)  
 .MODEL MMEDMOD NMOS (VTO = 2.38 KP = 12 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RS = 0.03 RG = 4)  
 .MODEL MSTROMOD NMOS (VTO = 2.87 KP = 28 LAMBDA = 0.02 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u)  
 .MODEL MWEAKMOD NMOS (VTO = 1.95 KP = 0.08 IS = 1e-30 N = 10 TOX = 1 L = 1u W = 1u RG = 40 RS = 0.1)  
 .MODEL RBREAKMOD RES (TC1 = 9.7e-4 TC2 = 0)  
 .MODEL RDRAINMOD RES (TC1 = 9.8e-3 TC2 = 2.85e-5)  
 .MODEL RSLCMOD RES (TC1 = 5e-3 TC2 = 5.05e-6)  
 .MODEL RSOURCEMOD RES (TC1 = 1.5e-3 TC2 = 1e-6)  
 .MODEL RVTHRESMOD RES (TC1 = -1.48e-3 TC2 = -5e-6)  
 .MODEL RVTEMPMOD RES (TC1 = -1.68e-3 TC2 = 8e-7)

.MODEL S1AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -4.7 VOFF = -2.0)  
 .MODEL S1BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -2.0 VOFF = -4.7)  
 .MODEL S2AMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = -1.0 VOFF = 0.3)  
 .MODEL S2BMOD VSWITCH (RON = 1e-5 ROFF = 0.1 VON = 0.3 VOFF = -1.0)

.ENDS

NOTE: For further discussion of the PSpICE model, consult **A New PSpICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.





**SPICE Thermal Model**

REV 16 March 2000

T76009

CTHERM1 th 6 9.5e-4  
 CHERM2 6 5 2.4e-3  
 CHERM3 5 4 3.9e-3  
 CHERM4 4 3 4.3e-3  
 CHERM5 3 2 5.9e-3  
 CHERM6 2 tl 3.0e-2

RHERM1 th 6 2.0e-2  
 RHERM2 6 5 1.1e-1  
 RHERM3 5 4 2.75e-1  
 RHERM4 4 3 5.3e-1  
 RHERM5 3 2 7.1e-1  
 RHERM6 2 tl 7.8e-1

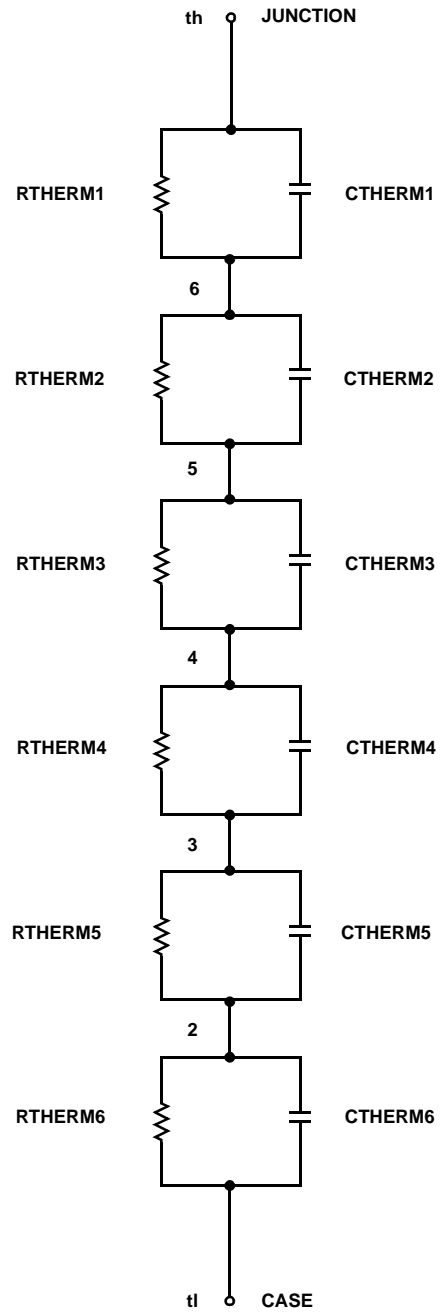
**SABER Thermal Model**

SABER thermal model T76009

template thermal\_model th tl  
 thermal\_c th, tl

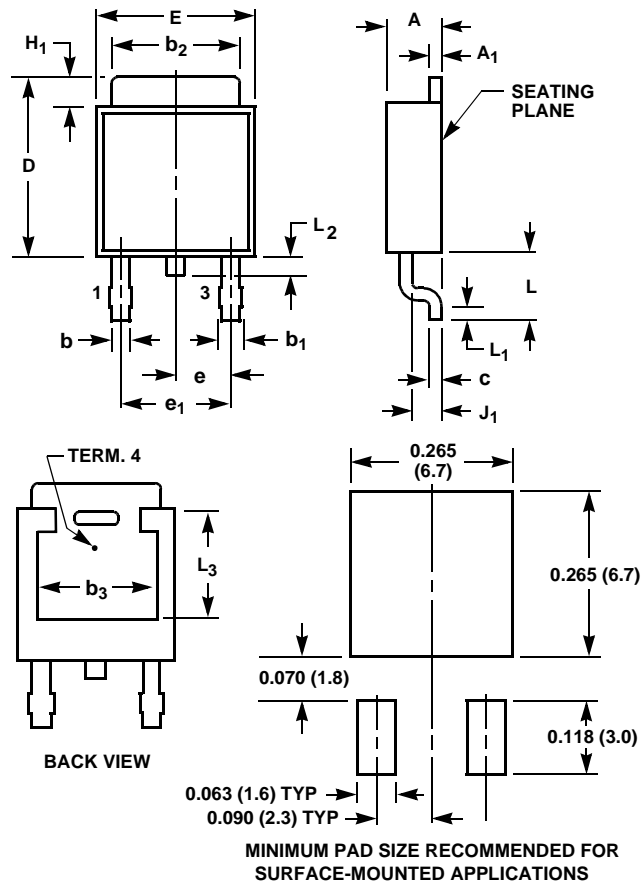
```
{
ctherm.ctherm1 th 6 = 9.5e-4
ctherm.ctherm2 6 5 = 2.4e-3
ctherm.ctherm3 5 4 = 3.9e-3
ctherm.ctherm4 4 3 = 4.3e-3
ctherm.ctherm5 3 2 = 5.9e-3
ctherm.ctherm6 2 tl = 3.0e-2
```

```
rtherm.rtherm1 th 6 = 2.0e-2
rtherm.rtherm2 6 5 = 1.1e-1
rtherm.rtherm3 5 4 = 2.75e-1
rtherm.rtherm4 4 3 = 5.3e-1
rtherm.rtherm5 3 2 = 7.1e-1
rtherm.rtherm6 2 tl = 7.8e-1
}
```



**TO-252AA**

**SURFACE MOUNT JEDEC TO-252AA PLASTIC PACKAGE**



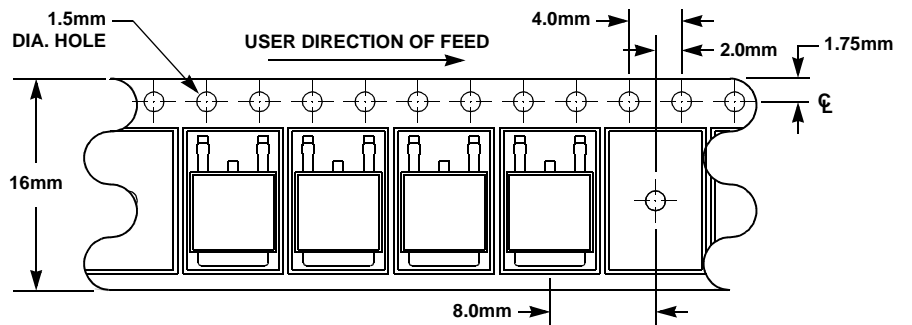
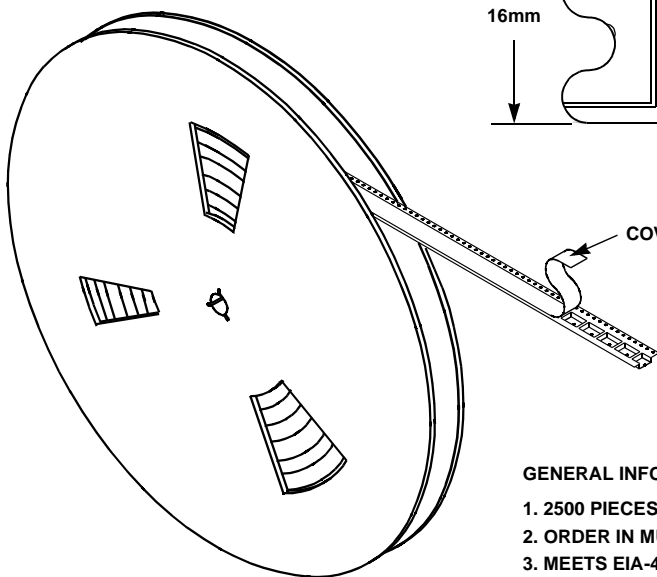
SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.086	0.094	2.19	2.38	-
A <sub>1</sub>	0.018	0.022	0.46	0.55	4, 5
b	0.028	0.032	0.72	0.81	4, 5
b <sub>1</sub>	0.033	0.045	0.84	1.14	4
b <sub>2</sub>	0.205	0.215	5.21	5.46	4, 5
b <sub>3</sub>	0.190	-	4.83	-	2
c	0.018	0.022	0.46	0.55	4, 5
D	0.270	0.295	6.86	7.49	-
E	0.250	0.265	6.35	6.73	-
e	0.090 TYP		2.28 TYP		7
e <sub>1</sub>	0.180 BSC		4.57 BSC		7
H <sub>1</sub>	0.035	0.045	0.89	1.14	-
J <sub>1</sub>	0.040	0.045	1.02	1.14	-
L	0.100	0.115	2.54	2.92	-
L <sub>1</sub>	0.020	-	0.51	-	4, 6
L <sub>2</sub>	0.025	0.040	0.64	1.01	3
L <sub>3</sub>	0.170	-	4.32	-	2

**NOTES:**

1. These dimensions are within allowable dimensions of Rev. B of JEDEC TO-252AA outline dated 9-88.
2. L<sub>3</sub> and b<sub>3</sub> dimensions establish a minimum mounting surface for terminal 4.
3. Solder finish uncontrolled in this area.
4. Dimension (without solder).
5. Add typically 0.002 inches (0.05mm) for solder plating.
6. L<sub>1</sub> is the terminal length for soldering.
7. Position of lead to be measured 0.090 inches (2.28mm) from bottom of dimension D.
8. Controlling dimension: Inch.
9. Revision 11 dated 1-00.

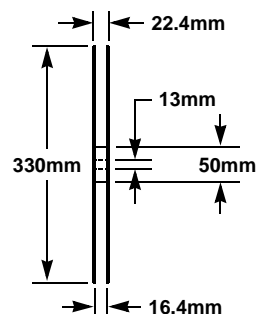
**TO-252AA**

**16mm TAPE AND REEL**



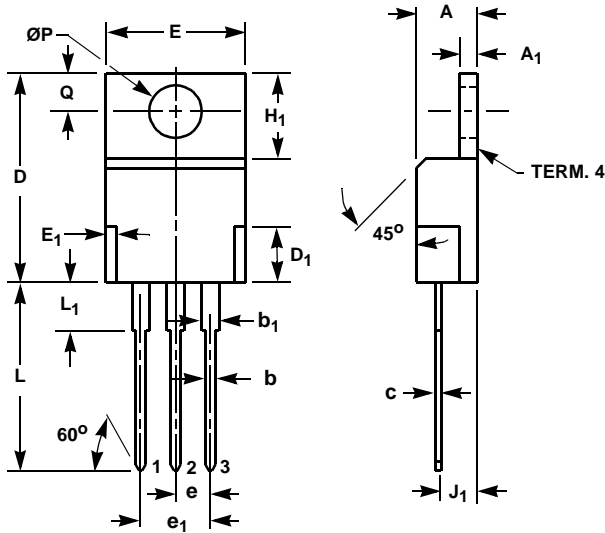
**GENERAL INFORMATION**

1. 2500 PIECES PER REEL.
2. ORDER IN MULTIPLES OF FULL REELS ONLY.
3. MEETS EIA-481 REVISION "A" SPECIFICATIONS.



**TO-220AB**

**3 LEAD JEDEC TO-220AB PLASTIC PACKAGE**



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.170	0.180	4.32	4.57	-
A <sub>1</sub>	0.048	0.052	1.22	1.32	-
b	0.030	0.034	0.77	0.86	3, 4
b <sub>1</sub>	0.045	0.055	1.15	1.39	2, 3
c	0.014	0.019	0.36	0.48	2, 3, 4
D	0.590	0.610	14.99	15.49	-
D <sub>1</sub>	-	0.160	-	4.06	-
E	0.395	0.410	10.04	10.41	-
E <sub>1</sub>	-	0.030	-	0.76	-
e	0.100 TYP		2.54 TYP		5
e <sub>1</sub>	0.200 BSC		5.08 BSC		5
H <sub>1</sub>	0.235	0.255	5.97	6.47	-
J <sub>1</sub>	0.100	0.110	2.54	2.79	6
L	0.530	0.550	13.47	13.97	-
L <sub>1</sub>	0.130	0.150	3.31	3.81	2
ØP	0.149	0.153	3.79	3.88	-
Q	0.102	0.112	2.60	2.84	-

**NOTES:**

1. These dimensions are within allowable dimensions of Rev. J of JEDEC TO-220AB outline dated 3-24-87.
2. Lead dimension and finish uncontrolled in L<sub>1</sub>.
3. Lead dimension (without solder).
4. Add typically 0.002 inches (0.05mm) for solder coating.
5. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
6. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
7. Controlling dimension: Inch.
8. Revision 2 dated 7-97.

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